

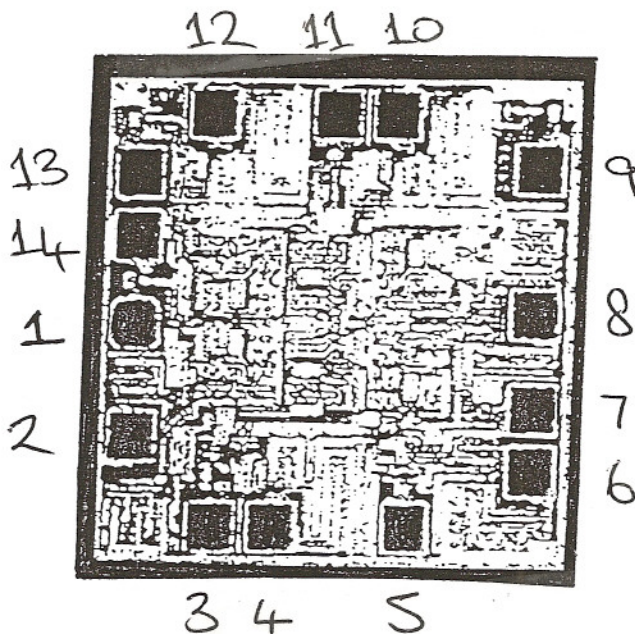


# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>Pad</u>	<u>Function</u>	<u>Pad</u>	<u>Function</u>
1	IN 1	8	OUT 4
2	OUT 1	9	IN 4
3	IN 2	10	OUT 5
4	OUT 2	11	IN 5
5	IN 3	12	OUT 6
6	OUT 3	13	IN 6
7	V <sub>SS</sub>	14	V <sub>DD</sub>

Top Material:  
 Backside Material:  
 Bond Pad Size:  
 Backside Potential:  
 Mask Ref:

APPROVED BY: MG

DIE SIZE : 60 x 59 x 20

DATE: 10/23/08

MFG: MOTOROLA

THICKNESS:

P/N: CD4106BH